

# **AN9520**

## **Multilayer Chip Antenna for 2.4GHz Wireless Communication**



# AN9520 Multilayer Chip Antenna

## ◆ Features

- Light weight and low profile 9.5mm(L)X2.1mm(W)X1.0mm(H)
  - Omni-directional in azimuth
- Lead (Pb) Free

## ◆ Applications

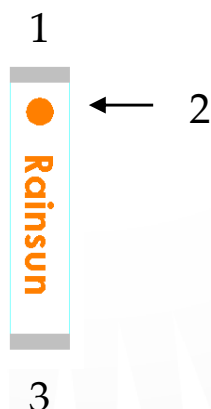
- 2.4GHz wireless communications
  - 2.4GHz Modules
  - Bluetooth System
- 802.11b/g Wireless LAN System

## Specifications

|                       |                  |
|-----------------------|------------------|
| Center frequency      | 2.365-2.567GHz   |
| Peak gain             | 1.5dBi           |
| Operation temperature | -40 ~ +85 °C     |
| Storage temperature   | -40 ~ +85 °C     |
| VSWR                  | 2.0 (max)        |
| Input Impedance       | 50 Ohm           |
| Power handling        | 3W (max)         |
| Bandwidth             | 200MHz           |
| Azimuth beamwidth     | Omni-directional |
| Polarization          | Linear           |

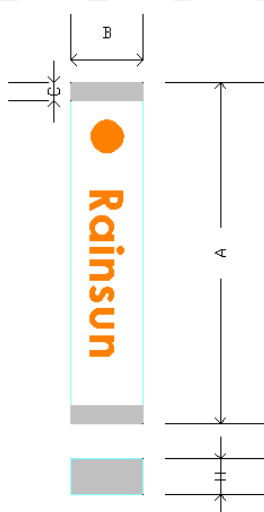
## Pin configuration

Top view



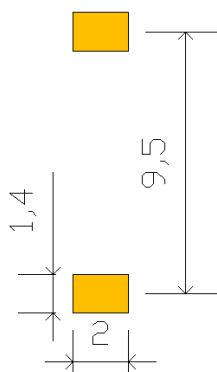
| Pin No | Pin assignment     |
|--------|--------------------|
| 1      | Feed termination   |
| 2      | Feed point mark    |
| 3      | Solder termination |

## Dimensions



| Symbol | Dimensions(mm)  |
|--------|-----------------|
| A      | $9.50 \pm 0.10$ |
| B      | $2.10 \pm 0.10$ |
| C      | $0.65 \pm 0.05$ |
| H      | $1.00 \pm 0.20$ |

## PCB foot printer



## Recommended Test Board Pattern

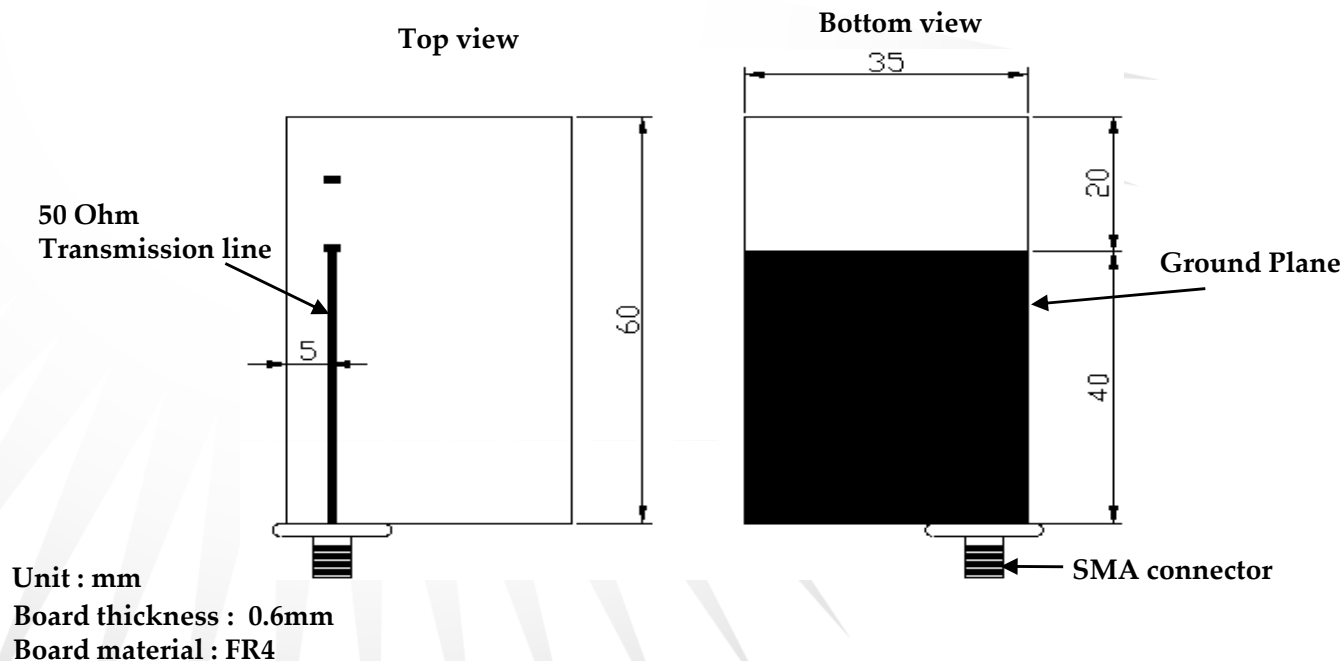
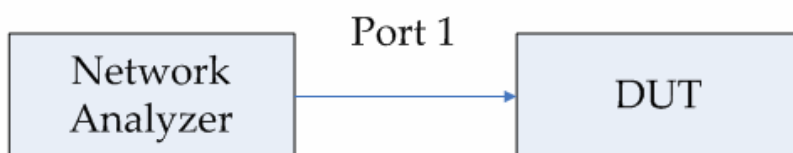


Fig-1

## Testing Setup



## Measurement



### Testing Instrument:

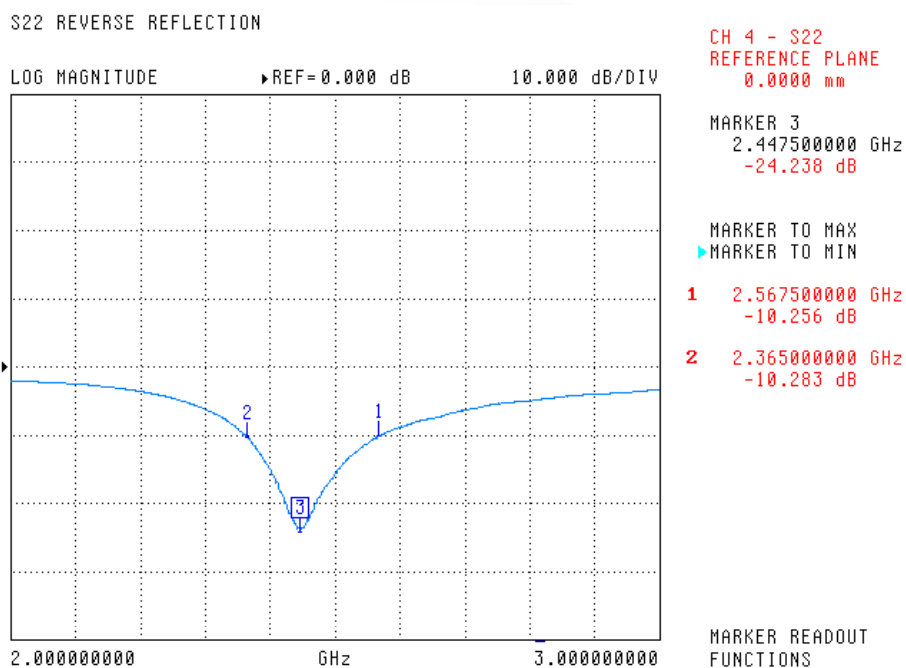
Anritsu 37369C VNA(Vector Network Analyzer)

VNA calibrate with 1 path reflection only calibration sequence on test board feed point.

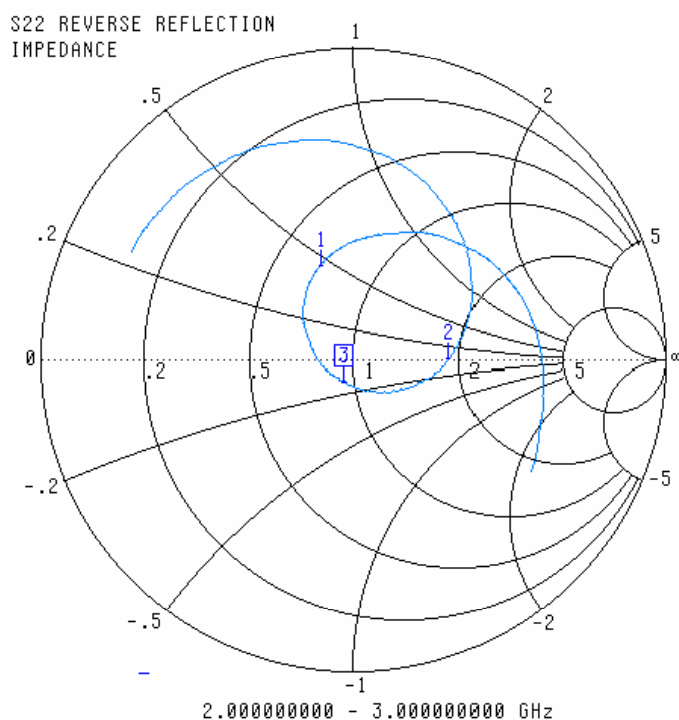
The test board dimension and it's layout is the same as Fig-1.

# Typical Electrical Characteristics

## Return loss



## Smith Chart

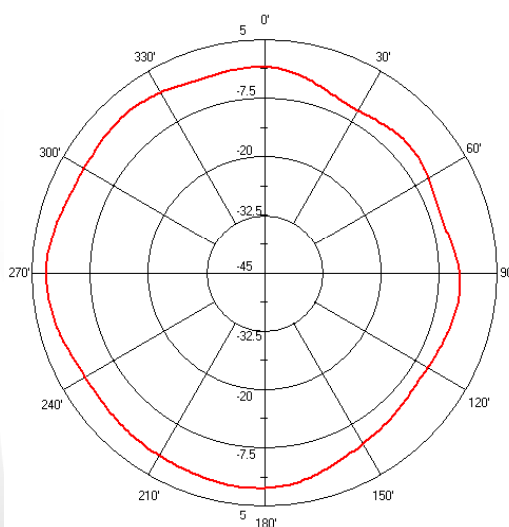


### Marker data:

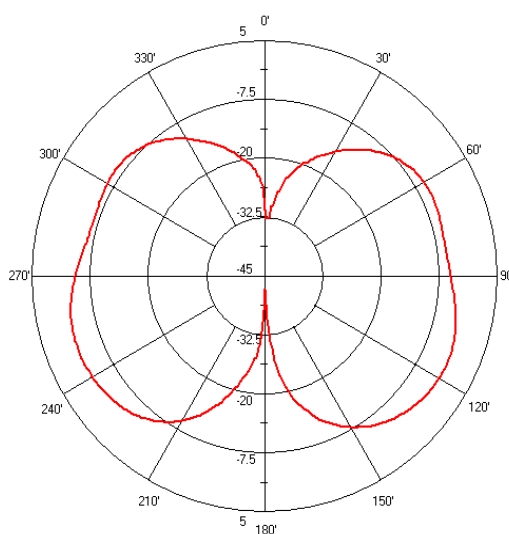
- 1 : f=2.567 GHz
- 2 : f=2.365 GHz
- 3 : f=2.447 GHz

## Typical Radiation Patterns

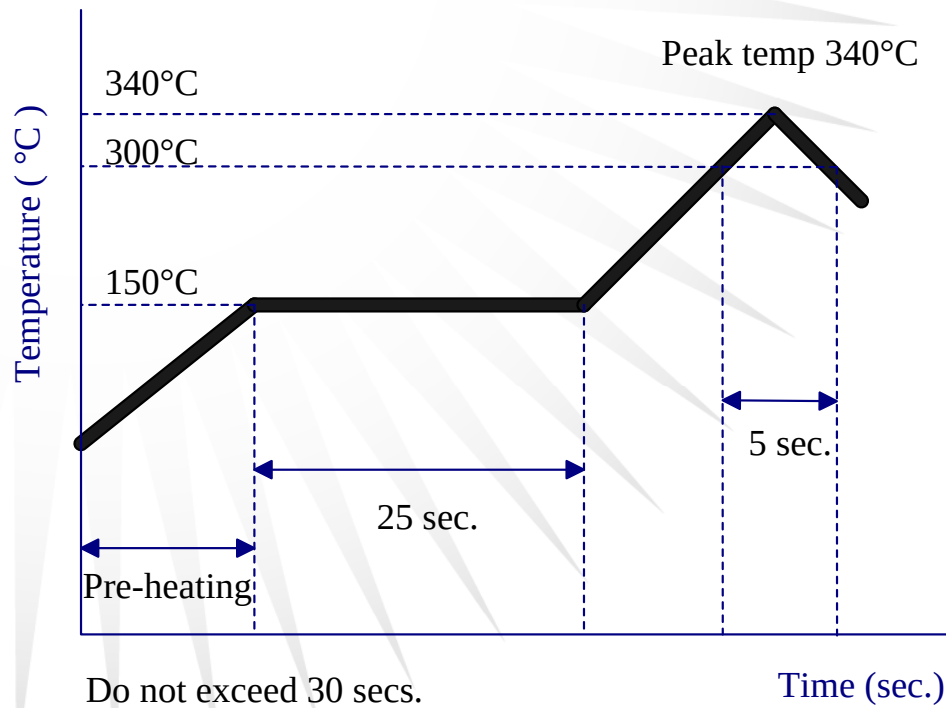
### 2.45 GHz H-Plane



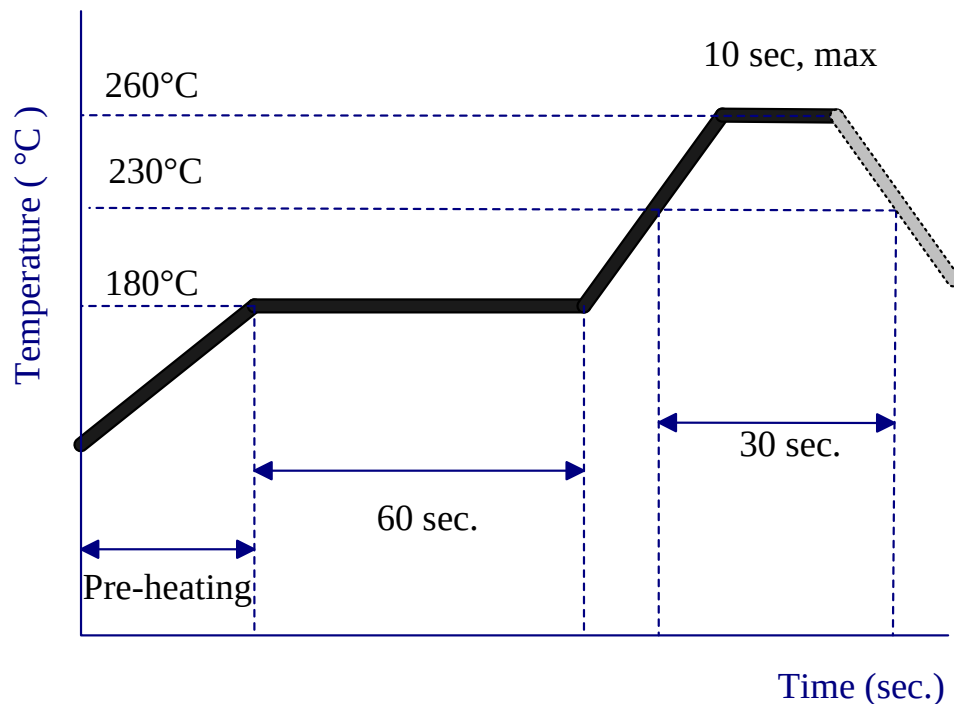
### 2.45 GHz E-Plane



## Typical Soldering Profile for Lead-free Process

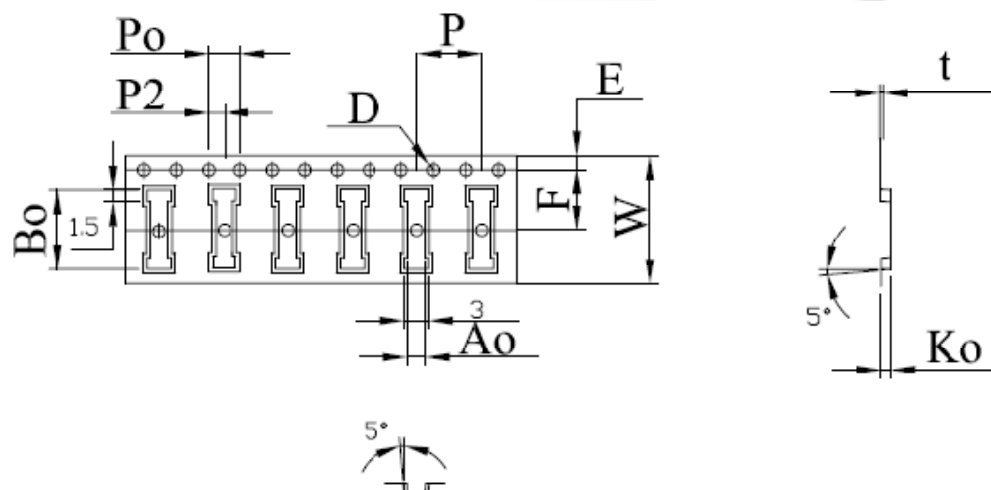


### Reflow Soldering



# Packing

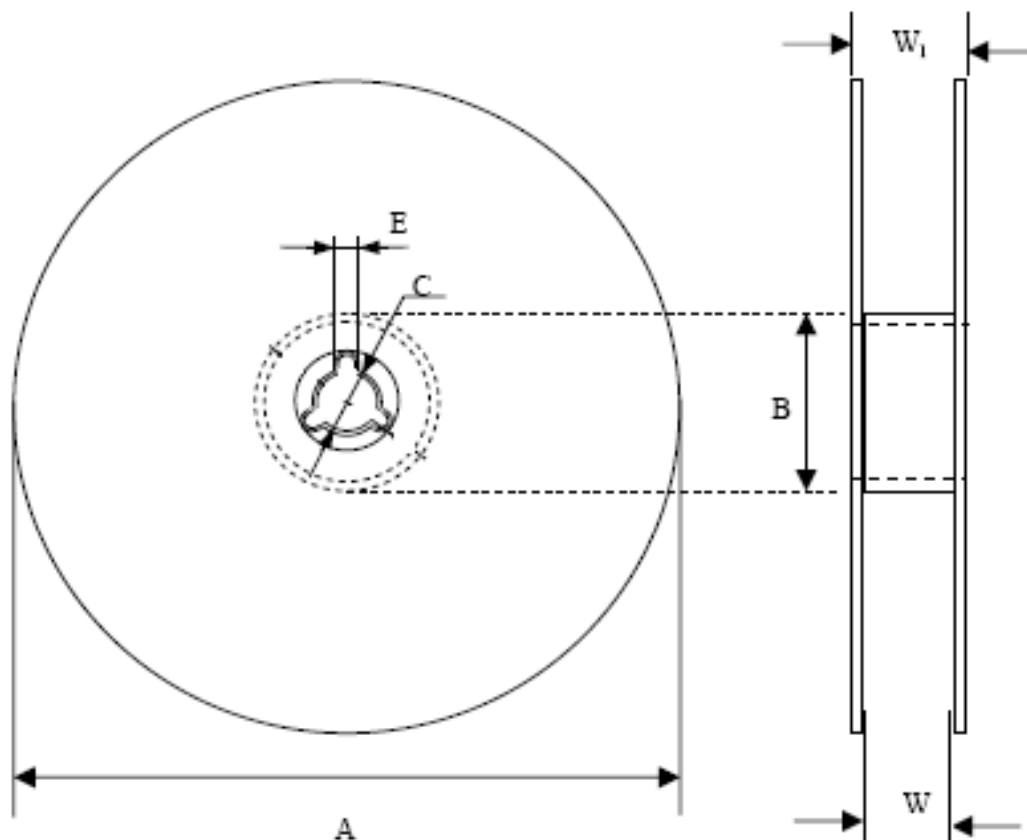
## Blister Tape Specifications



| Symbol | Dimension | Tolerance        | Unit |
|--------|-----------|------------------|------|
| W      | 16.00     | $\pm 0.30$       | mm   |
| E      | 1.75      | $\pm 0.10$       | mm   |
| F      | 7.50      | $\pm 0.10$       | mm   |
| D      | 1.50      | + 0.10<br>- 0.00 | mm   |
| $D_1$  | 1.50      | + 0.25<br>- 0.00 | mm   |
| $P_0$  | 4.00      | $\pm 0.10$       | mm   |
| P      | 8.00      | $\pm 0.10$       | mm   |
| $P_2$  | 2.00      | $\pm 0.10$       | mm   |
| $A_0$  | 2.20      | $\pm 0.10$       | mm   |
| $B_0$  | 10.00     | $\pm 0.10$       | mm   |
| $K_0$  | 1.20      | $\pm 0.10$       | mm   |
| t      | 0.30      | $\pm 0.05$       | mm   |



## Reel Specifications



| Quantity<br>Per Reel | Tape Width<br>(mm) | A<br>(mm) | C<br>(mm) | B<br>(mm) | E<br>(mm) | W<br>(mm) | W <sub>1</sub><br>(mm) |
|----------------------|--------------------|-----------|-----------|-----------|-----------|-----------|------------------------|
| 1,500                | 16                 | 180±1     | 13.0±0.5  | 62±0.5    | 2.2±0.5   | 16±0.5    | 20±0.2                 |